



Sonics Marks Licensee Milestone with Total Shipments Surpassing 500 Million Units

Proliferation of SoC Design Drives World's Leading Interconnect IP Company; CEO Shares Business Success, Insights at This Week's Semico Summit

MEDIA CONTACT:

Mary Jane Reiter
Fast Forward PR for
Sonics, Inc.
+1 408 725 1239
mjreiter@sbcglobal.net

- **Newsroom**
- 2009 News Releases
- 2008 News Releases
- 2007 News Releases
- 2006 News Releases
- News Coverage
- Upcoming Events
- Media Kit

MILPITAS, Calif., – March 9, 2009 – Sonics, Inc., a premier supplier of system-on-chip SMART Interconnect™ solutions, has announced that the company's cumulative licensee shipments surpassed the 500 million unit mark at the end of 2008. For more than a decade, Sonics has been shipping its solutions to leading semiconductor companies including Texas Instruments, Broadcom Corp., Samsung and Toshiba. Today, as more companies embrace SoC design and incorporate multiple intellectual property (IP) blocks on-chip, Sonics remains poised for continued growth in the digital entertainment, wireless and mobile markets.

As a result of its success over the last 12 years, Grant Pierce, Sonics CEO, has been invited to participate in the Semico Summit 2009 in Scottsdale, Ariz. He will be part of a March 10 panel hosted by Mentor Graphics' Chairman and CEO, Walden Rhines, entitled: "What are the Attributes of a Successful Company?" Pierce will share his insights on rules for customer engagement in the new global economy, as well as strategic success factors for semiconductor companies competing in a disruptive and dynamic market.

"Sonics' success with many of the world's top semiconductor suppliers has been achieved by delivering three generations of proven silicon solutions that address critical on-chip interconnect issues and leveraging their unique platform strategies," said Pierce. "This success has not gone unnoticed as we continue to partner with new semiconductor leaders worldwide who remain focused on design innovation and maintaining global prominence across the digital consumer, wireless and mobile markets."

Sonics provides SoC designers with the largest portfolio of on-chip connectivity solutions uniquely designed to optimize memory access, seamlessly manage network traffic and increase system performance. Its solutions enable designers to quickly mix and match various IP blocks without concern for individual IP implementations by abstracting information such as bus width, protocol and eliminating complexities in the interconnect. In turn, this enables right-by-design methodologies starting at SystemC architecture models that match the RTL and verification test benches used for final timing closure at tape out.

About Sonics

Sonics, Inc. provides SoC designers with critical semiconductor IP that is uniquely designed to optimize memory access and increase SoC performance in advanced digital consumer, wireless and mobile devices. Sonics' customers see the benefits of high design predictability and increased design efficiency. The company's broad array of on-chip connectivity solutions address the growing complexity found in consumer devices with advanced voice, data and video features. Major semiconductor and systems companies, including Broadcom, Samsung, Texas Instruments and Toshiba, leverage Sonics' technology in leading products in the wireless, digital multimedia and communications markets. For more information please visit www.sonicsinc.com.

#

©Sonics, Inc., the company's logo, and SMART Interconnect are registered trademarks of Sonics, Inc. All other trademarks are the property of their respective owners.